8-Bit Serial-Input/Serial or Parallel-Output Shift Register with Latched 3-State Outputs

High-Performance Silicon-Gate CMOS

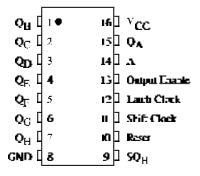
The SL74HC595 is identical in pinout to the LS/ALS595. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALSTTL outputs.

The SL74HC595 consists of an 8-bit shift register and an 8-bit D-type latch with three-state parallel outputs. The shift register accepts serial data and provides a serial output. The shift register also provides parallel data to the 8bit latch. The shift register and latch have independent clock inputs. This device also has an asynchronous reset for the shift register.

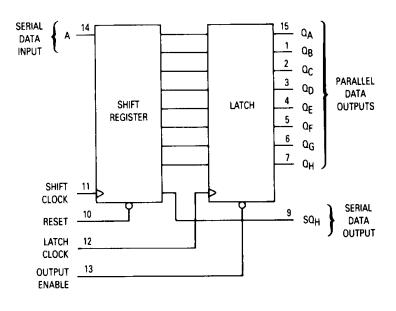
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices

V SUFFIX PLASTIC N SUFFIX PLASTIC D SUFFIX SOM: ORDERING INFORMATION SL74HC595N Plastic SL74HC595D SOIC T_A = -55° to 125° C for all packages

PIN ASSIGNMENT



LOGIC DIAGRAM



PIN $16 = V_{CC}$ PIN 8 = GND

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
$V_{\rm IN}$	DC Input Voltage (Referenced to GND)	-1.5 to V _{CC} +1.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Current, per Pin	±35	mA
I_{CC}	DC Supply Current, V _{CC} and GND Pins	±75	mA
P_{D}	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
Tstg	Storage Temperature	-65 to +150	°C
$T_{\rm L}$	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

^{*}Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

SOIC Package: : - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
$V_{\rm IN}, V_{\rm OUT}$	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_{A}	Operating Temperature, All Package Types	-55	+125	°C
t _r , t _f	Input Rise and Fall Time (Figure 1) $V_{CC} = 2.0 \text{ V} \\ V_{CC} = 4.5 \text{ V} \\ V_{CC} = 6.0 \text{ V}$	0 0 0	1000 500 400	ns

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, $V_{\rm IN}$ and $V_{\rm OUT}$ should be constrained to the range ${\rm GND} \leq (V_{\rm IN} \ {\rm or} \ V_{\rm OUT}) \leq V_{\rm CC}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

⁺Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

		V _{CC} Guaranteed Limit					
Symbol	Parameter	Test Conditions	V	25 °C to -55°C	≤85 °C	≤125 °C	Unit
V_{IH}	Minimum High-Level Input Voltage	V_{OUT} =0.1 V or V_{CC} -0.1 V $I_{OUT}I \le 20 \mu\text{A}$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
$V_{\rm IL}$	Maximum Low -Level Input Voltage	V_{OUT} =0.1 V or V_{CC} -0.1 V $I_{OUT}I \le 20 \mu A$	2.0 4.5 6.0	0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V
V_{OH}	$\begin{array}{c} \mbox{Minimum High-Level} \\ \mbox{Output Voltage, } \mbox{Q}_{\mbox{\scriptsize A}} - \\ \mbox{Q}_{\mbox{\scriptsize H}} \end{array}$	$V_{IN}=V_{IH}$ or V_{IL} $\mid I_{OUT} \mid \leq 20 \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$\begin{aligned} &V_{\rm IN} {=} V_{\rm IH} \text{ or } V_{\rm IL} \\ &\mid I_{\rm OUT} \mid \leq 6.0 \text{ mA} \\ &\mid I_{\rm OUT} \mid \leq 7.8 \text{ mA} \end{aligned}$	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	
$ m V_{OL}$	$\begin{array}{c} \text{Maximum Low-Level} \\ \text{Output Voltage, } Q_{\text{A}}\text{-} \\ Q_{\text{H}} \end{array}$	$V_{IN}=V_{IH} \text{ or } V_{IL}$ $\mid I_{OUT} \mid \leq 20 \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{\rm IN} = V_{\rm IH} \text{ or } V_{\rm IL}$ $\mid I_{\rm OUT} \mid \le 6.0 \text{ mA}$ $\mid I_{\rm OUT} \mid \le 7.8 \text{ mA}$	4.5 6.0	0.26 0.26	0.33 0.33	0.4 0.4	
$V_{ m OH}$	Minimum High-Level Output Voltage, SQ _H	$V_{IN}=V_{IH} \text{ or } V_{IL}$ $\mid I_{OUT} \mid \leq 20 \ \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{\rm IN} = V_{\rm IH} \text{ or } V_{\rm IL}$ $\mid I_{\rm OUT} \mid \le 4.0 \text{ mA}$ $\mid I_{\rm OUT} \mid \le 5.2 \text{ mA}$	4.5 6.0	3.98 5.48	3.84 5.34	3.7 5.2	
V_{OL}	Maximum Low-Level Output Voltage, SQ _H	$\begin{aligned} &V_{\rm IN} {=} V_{\rm IH} \text{ or } V_{\rm IL} \\ &\mid I_{\rm OUT} \mid \leq 20 \ \mu A \end{aligned}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$\begin{aligned} & V_{\rm IN} {=} V_{\rm IH} \text{ or } V_{\rm IL} \\ & \mid I_{\rm OUT} \mid \leq 4.0 \text{ mA} \\ & \mid I_{\rm OUT} \mid \leq 5.2 \text{ mA} \end{aligned}$	4.5 6.0	0.26 0.26	0.33 0.33	0.4 0.4	
$I_{\rm IN}$	Maximum Input Leakage Current	V _{IN} =V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μΑ
I_{OZ}	Maximum Three-State Leakage Current, Q _A - Q _H	Output in High-Impedance State $V_{IN} = V_{IL} \text{ or } V_{IH} $ $V_{IN} = V_{CC} \text{ or GND}$	6.0	±0.5	±5.0	±10	μА
I_{CC}	Maximum Quiescent Supply Current (per Package)	$V_{\rm IN} = V_{\rm CC}$ or GND $I_{\rm OUT} = 0 \mu A$	6.0	4.0	40	160	μА

$\textbf{AC ELECTRICAL CHARACTERISTICS}(C_L = 50 pF, Input \ t_r = t_f = 6.0 \ ns)$

		V_{CC}	Gu	aranteed Li	mit	
Symbol	Parameter	V	25 °C to -55°C	≤85 °C	≤125 °C	Unit
f_{max}	Minimum Clock Frequency (50% Duty Cycle) (Figures 1 and 7)	2.0 4.5 6.0	6.0 30 35	4.8 24 28	4.0 20 24	MHz
$t_{\rm PLH},t_{ m PHL}$	Maximum Propagation Delay, Shift Clock to SQ _H (Figures 1 and 7)	2.0 4.5 6.0	140 28 24	175 35 30	210 42 36	ns
t _{PHL}	Maximum Propagation Delay , Reset to $SQ_{\rm H}$ (Figures 2 and 7)	2.0 4.5 6.0	145 29 25	180 36 31	220 44 38	ns
$t_{\rm PLH}, t_{\rm PHL}$	Maximum Propagation Delay , Latch Clock to $Q_{\text{A}}\text{-}Q_{\text{H}}$ (Figures 3 and 7)	2.0 4.5 6.0	140 28 24	175 35 30	210 42 36	ns
$t_{\rm PLZ}, t_{\rm PHZ}$	Maximum Propagation Delay , Output Enable to $Q_{A}\text{-}Q_{H}$ (Figures 4 and 8)	2.0 4.5 6.0	150 30 26	190 38 33	225 45 38	ns
$t_{\rm PZL}, t_{\rm PZH}$	Maximum Propagation Delay , Output Enable to $Q_{A}\text{-}Q_{H}$ (Figures 4 and 8)	2.0 4.5 6.0	135 27 23	170 34 29	205 41 35	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Q_A - Q_H (Figures 3 and 7)	2.0 4.5 6.0	60 12 10	75 15 13	90 18 15	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, SQ _H (Figures 1 and 7)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C _{IN}	Maximum Input Capacitance	-	10	10	10	pF
C _{OUT}	Maximum Three-State Output Capacitance (Output in High-Impedance State), Q _A -Q _H	-	15	15	15	pF

	Power Dissipation Capacitance (Per Package)	Typical @25°C,V _{CC} =5.0 V	
C_{PD}	Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^{-2} f + I_{CC} V_{CC}$	300	pF

$\textbf{TIMING REQUIREMENTS}(C_L = 50 pF, Input \ t_r = t_f = 6.0 \ ns)$

		V_{CC}	Guara	Guaranteed Limit		
Symbol	Parameter	V	25 °C to -55°C	≤85°C	≤125°C	Unit
T_{su}	Minimum Setup Time,Serial Data Input A to Shift Clock (Figure 5)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
T_{su}	Minimum Setup Time, Shift Clock to Latch Clock (Figure 6)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
t_h	Minimum Hold Time, Shift Clock to Serial Data Input A (Figure 5)	2.0 4.5 6.0	5 5 5	5 5 5	5 5 5	ns
$T_{\rm rec}$	Minimum Recovery Time, Reset Inactive to Shift Clock (Figure 2)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
T_{w}	Minimum Pulse Width, Reset (Figure 2)	2.0 4.5 6.0	60 12 10	75 15 13	90 18 15	ns
T_{w}	Minimum Pulse Width, Shift Clock (Figure 1)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
$T_{ m w}$	Minimum Pulse Width, Latch Clock (Figure 6)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
t _r , t _f	Maximum Input Rise and Fall Times (Figure 1)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

FUNCTION TABLE

			Inputs	S		Resulting Function				
Operation	Reset	Serial Input A	Shift Clock	Latch Clock	Output Enable	Shift Register Contents	Latch Register Contents	Serial Output SQ _H	Parallel Outputs Q _A -Q _H	
Reset shift register	L	X	X	<u>L</u> ,H,	L	L	U	L	U	
Shift data into shift register	Н	D	\	<u>L</u> ,H,	L	$D \stackrel{\blacktriangleright}{\triangleright} SR_A \\ SR_N \stackrel{\blacktriangleright}{\triangleright} SR_{N+1}$	U	SR _G →SR _H	U	
Shift register remains unchanged	Н	X	_L,H,	<u>L</u> ,H,	L	U	U	U	U	
Transfer shift register contents to latch register	Н	X	L,H,		L	U	SR_N LR _N	U	SR_N	
Latch register remains unchanged	X	X	X	L,H,	L	*	U	*	U	
Enable parallel outputs	X	X	X	X	L	*	**	*	Enabled	
Force outputs into high-impedance state	X	X	X	X	Н	*	**	*	Z	

SR = shift register contents

LR = latch register contents

D = data (L,H) logic level

U = remains unchanged

X = don't care

Z = high impedance

* = depends on Reset and Shift Clock inputs

** = depends on Latch Clock input

PIN DESCRIPTIONS

INPUTS:

A - Serial Data Input. The data on this pin is shifted into the 8-bit serial shift register.

CONTROL INPUTS:

Shift Clock - Shift Register Clock Input. A low-to-high transition on this input causes the data at the Serial Input pin to be shifted into the 8bit shift register.

Reset - Active-low, Asynchronous, Shift Register Reset Input. A low on this pin resets the shift register portion of this device only. The 8-bit latch is not affected.

Latch Clock - Storage Latch Clock Input. A low-tohigh transition on this input latches the shift register data.

Output Enable - Active-Low Output Enable. A low on this input allows the data from the latches to be presented at the outputs. A high on this input forces the outputs (Q_A-Q_H) into the high-impedance state. The serial output is not affected by this control unit.

OUTPUTS:

 $\mathbf{Q}_{\mathbf{A}}$ - $\mathbf{Q}_{\mathbf{H}}$ - Noninverted, 3-state, latch outputs.

 $\mathbf{SQ_H}$ - Voninverted, Serial Data Output. This is the output of the eighth stage of the 8-bit shift register. This output does not have three-state capability.

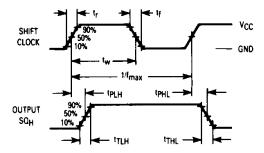


Figure 1. Switching Waveforms

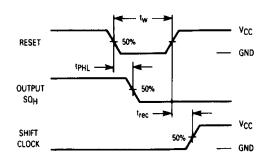


Figure 2. Switching Waveforms

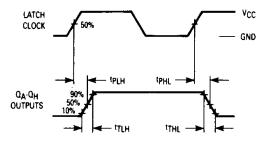


Figure 3. Switching Waveforms

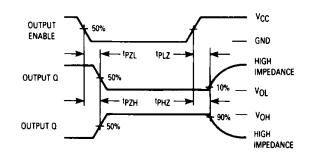


Figure 4. Switching Waveforms

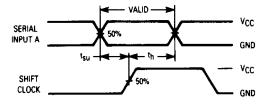


Figure 5. Switching Waveforms

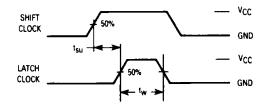
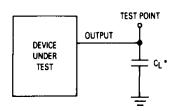


Figure 6. Switching Waveforms



*Includes all probe and jig capacitance.

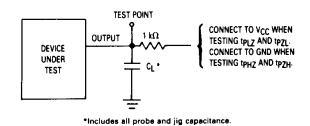
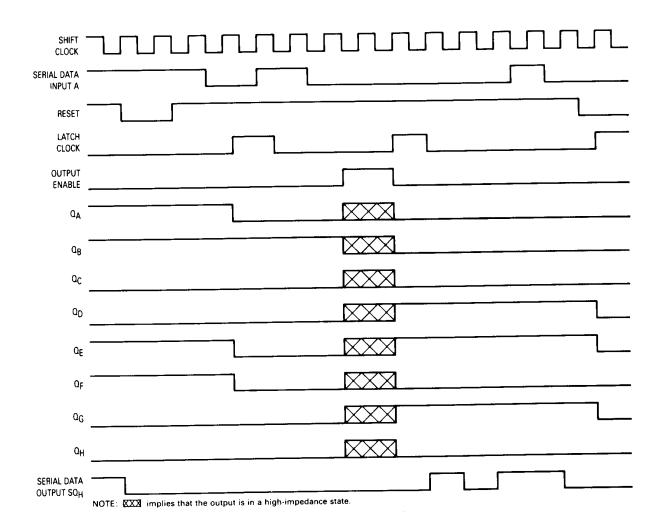


Figure 7. Test Circuit

Figure 8. Test Circuit

TIMING DIAGRAM



EXPANDED LOGIC DIAGRAM

